

DSEP29-06A



Pb Free Plating Product

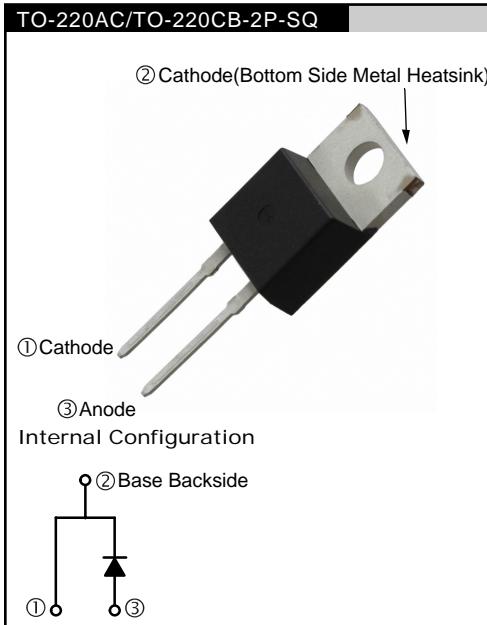
ThinkiSemi 30Amperes,600Volts SwitchMode Ultrafast Recovery Epitaxial Diode

APPLICATION

- Freewheeling, Snubber, Clamp
 - Inversion Welder
 - PFC
 - Plating Power Supply
 - Ultrasonic Cleaner and Welder
 - Converter & Chopper
 - UPS

PRODUCT FEATURE

- Ultrafast Recovery Time
 - Soft Recovery Characteristics
 - Low Recovery Loss
 - Low Forward Voltage
 - High Surge Current Capability
 - Low Leakage Current



GENERAL DESCRIPTION

DSEP29-06A using THINKISEMI lastest FRED FAB process(planar passivation pellet) with ultrafast and soft recovery characteristics.

ABSOLUTE MAXIMUM RATINGS

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PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Peak repetitive reverse voltage	V_{RRM}		600	V
Average rectified forward current in DC	$I_{F(AV)}$	$T_C = 130^\circ C$	30	A
Non-repetitive peak surge current	I_{FSM}	$T_J = 25^\circ C$	200	
Operating junction and storage temperatures	T_J, T_{Stg}		-65 to +175	°C

ELECTRICAL SPECIFICATIONS ($T_J = 25^\circ\text{C}$ unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage, blocking voltage	V_{BR} , V_R	$I_R = 100 \mu A$	600	-	-	V
Forward voltage	V_F	$I_F = 30 A$	-	1.4	2.0	
		$I_F = 30 A, T_J = 150^\circ C$	-	1.15	1.35	
Reverse leakage current	I_R	$V_R = V_R$ rated	-	0.02	30	μA
		$T_J = 150^\circ C, V_R = V_R$ rated	-	30	250	
Junction capacitance	C_T	$V_R = 600 V$	-	20	-	pF
Series inductance	L_S	Measured lead to lead 5 mm from package body	-	8	-	nH

DYNAMIC RECOVERY CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Reverse recovery time	t_{rr}	$I_F = 1 \text{ A}, dI_F/dt = 50 \text{ A}/\mu\text{s}, V_R = 30 \text{ V}$	-	30	45	ns
		$T_J = 25^\circ\text{C}$	-	45	-	
		$T_J = 125^\circ\text{C}$	-	100	-	
Peak recovery current	I_{RRM}	$T_J = 25^\circ\text{C}$	-	5.6	-	A
		$T_J = 125^\circ\text{C}$	-	10	-	
Reverse recovery charge	Q_{rr}	$T_J = 25^\circ\text{C}$	-	127	-	nC
		$T_J = 125^\circ\text{C}$	-	580	-	

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Maximum junction and storage temperature range	T_J, T_{Stg}		-65	-	175	°C
Thermal resistance, junction-to-case	R_{thJC}		-	0.84	1.3	°C/W
Thermal resistance, junction-to-ambient	R_{thJA}	Typical socket mount	-	-	70	
Typical thermal resistance, case-to-heatsink	R_{thCS}	Mounting surface, flat, smooth, and greased	-	0.5	-	
Weight			-	2	-	g
Mounting torque			-	0.07	-	oz.
Marking device		Case style 2L TO-220AC	DSEP29-06A			

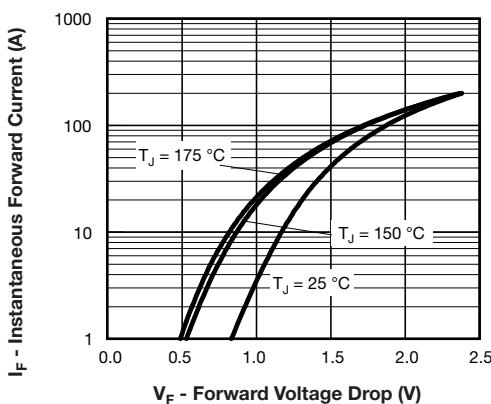


Fig. 1 - Typical Forward Voltage Drop Characteristics

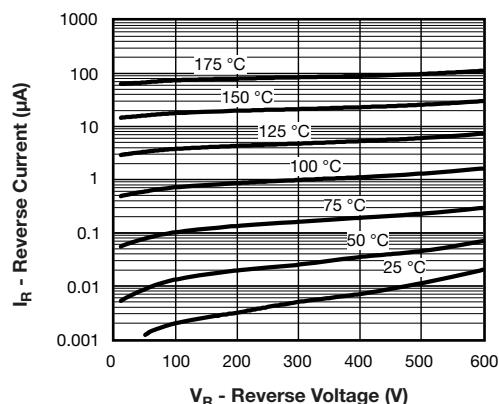


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

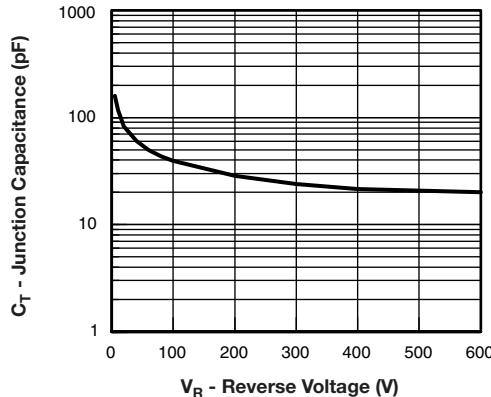


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

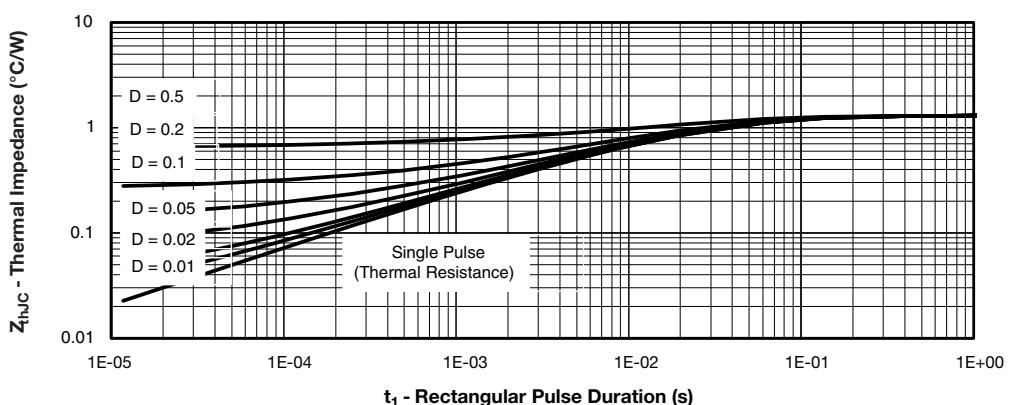


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

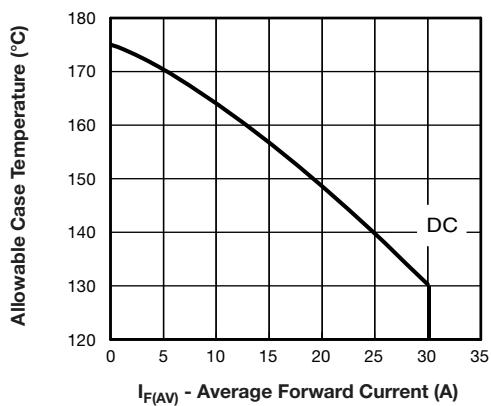


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

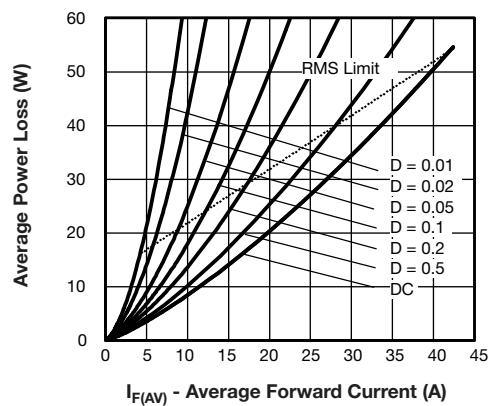


Fig. 6 - Forward Power Loss Characteristics

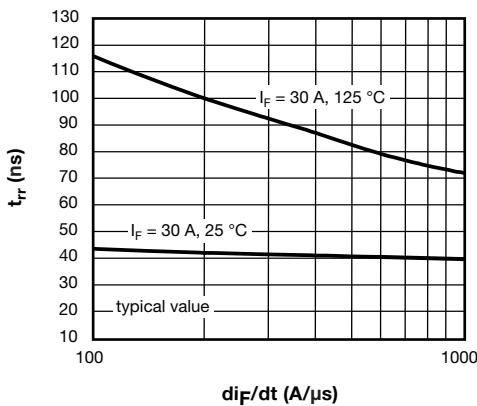


Fig. 7 - Typical Reverse Recovery vs. di_F/dt

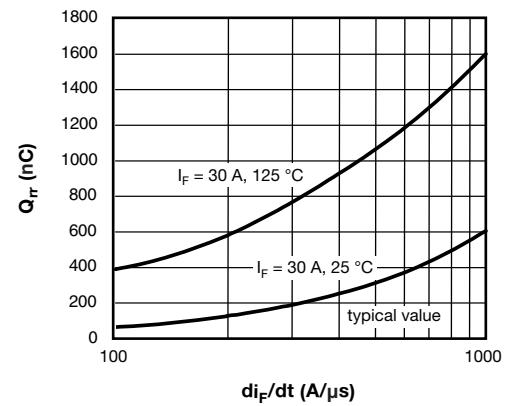


Fig. 8 - Typical Stored Charge vs. di_F/dt

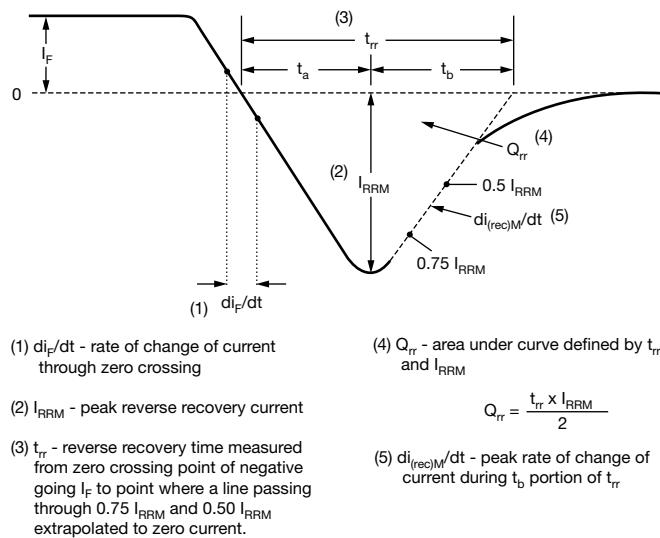
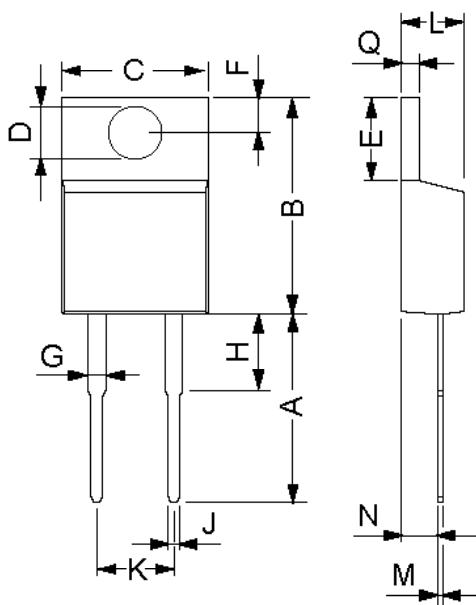


Fig. 9 - Reverse Recovery Waveform and Definitions

Mechanical Dimensions THINKI TO-220AC/TO-220CB-2P-SQ



Dim.	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	12.7	14.73	0.5	0.58
B	14.23	16.51	0.56	0.65
C	9.66	10.66	0.38	0.42
D	3.54	4.08	0.139	0.161
E	5.85	6.85	0.23	0.42
F	2.54	3.42	0.1	0.135
G	1.15	1.77	0.045	0.07
H	-	6.35	-	0.25
J	0.64	0.89	0.025	0.035
K	4.83	5.33	0.19	0.21
L	3.56	4.82	0.14	0.19
M	0.51	0.76	0.02	0.03
N	2.04	2.49	0.08	0.115
Q	0.64	1.39	0.025	0.055